

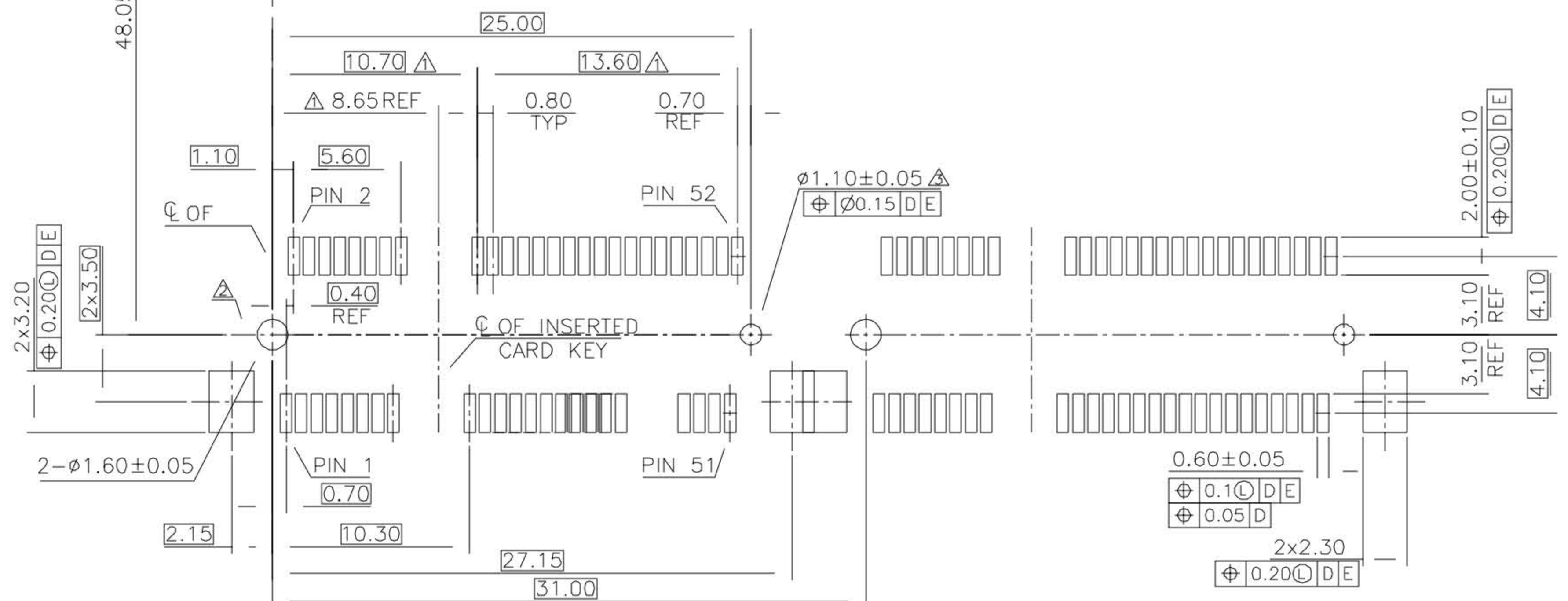
ASSIST METAL
PLATING

XX

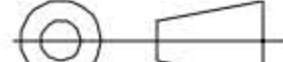
20: MATTE-TIN

65: GOLD FLASH 10 μ " OVER Ni 50 μ

THE HORIZONTAL AXIS, THROUGH THE
CENTER OF DATUM E.



SoniTexx

INETENDED USE CUSTOMER	TITLE	0.80MM PITCH MINI PCI EXPRESS H=8.0mm CONNECTOR CUSTOMER DRAWING				
TOLERANCES	PART NO.		APPRO	Mark		
LINEAR ^{0.0} ±0.30 ^{0.00} ±0.20 ANGLES±3°	DRAW NO.		CHKD	Steve		
	MATERIAL	SEE NOTE	DRAW	Tina		
	FINISH	SEE NOTE	DATE	08/05/09'		
	SCALE		SHEET		REV	UNIN
	1:1		1/1		A	mm
						

ASSIST METAL
PLATING

XX

20: MATTE-TIN 100μ" 20: MATTE-TIN
OVER Ni 50μ" 30: BRIGHT-TIN
30: BRIGHT-TIN 100μ"
OVER Ni 50μ"
51: SELECTION GOLD 1μ" OVER Ni 50μ"
52: SELECTION GOLD 5μ" OVER Ni 50μ"
61: GOLD FLASH 1μ" OVER Ni 50μ"
62: GOLD FLASH 3μ" OVER Ni 50μ"
63: GOLD FLASH 4μ" OVER Ni 50μ"
65: GOLD FLASH 10μ" OVER Ni 50μ"

51: SELECTION GOLD 1 μ " OVER Ni 50 μ "
52: SELECTION GOLD 5 μ " OVER Ni 50 μ "
61: GOLD FLASH 1 μ " OVER Ni 50 μ "
62: GOLD FLASH 3 μ " OVER Ni 50 μ "
63: GOLD FLASH 4 μ " OVER Ni 50 μ "
65: GOLD FLASH 10 μ " OVER Ni 50 μ "

THIS PART DON'T CONTAIN ANY SUBSTANCES

WHICH ARE SPECIFIED IN SS-00259

HOUSING : THERMO PLASTIC UL94V-0

CONTACT : COPPER ALLOY

SOLDER PEG :COPPER ALLOY

SPECIFICATION

CURRENT RATING : 0.5A 50V AC/DC

CONTACT RESISTANCE : 55 mΩ

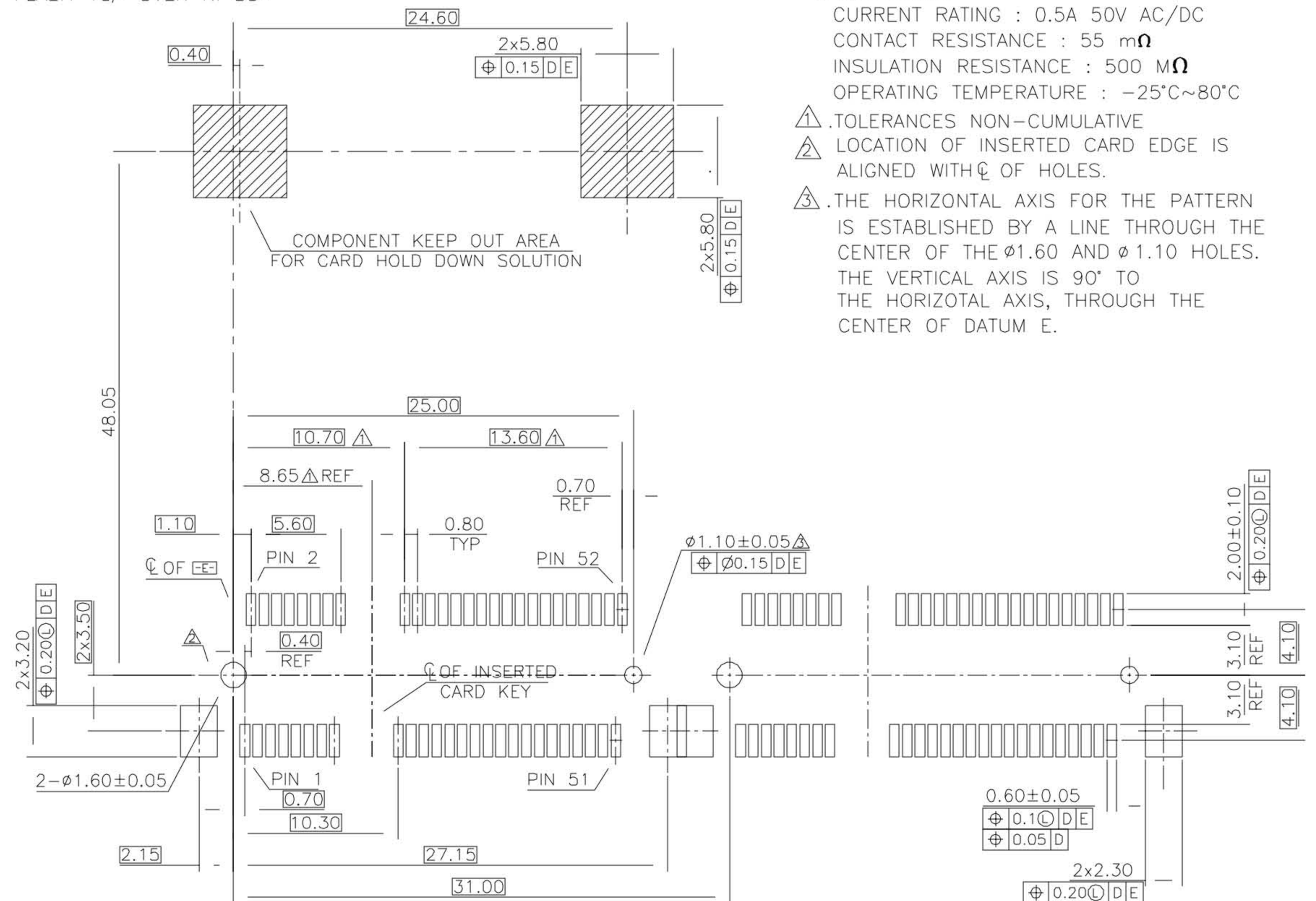
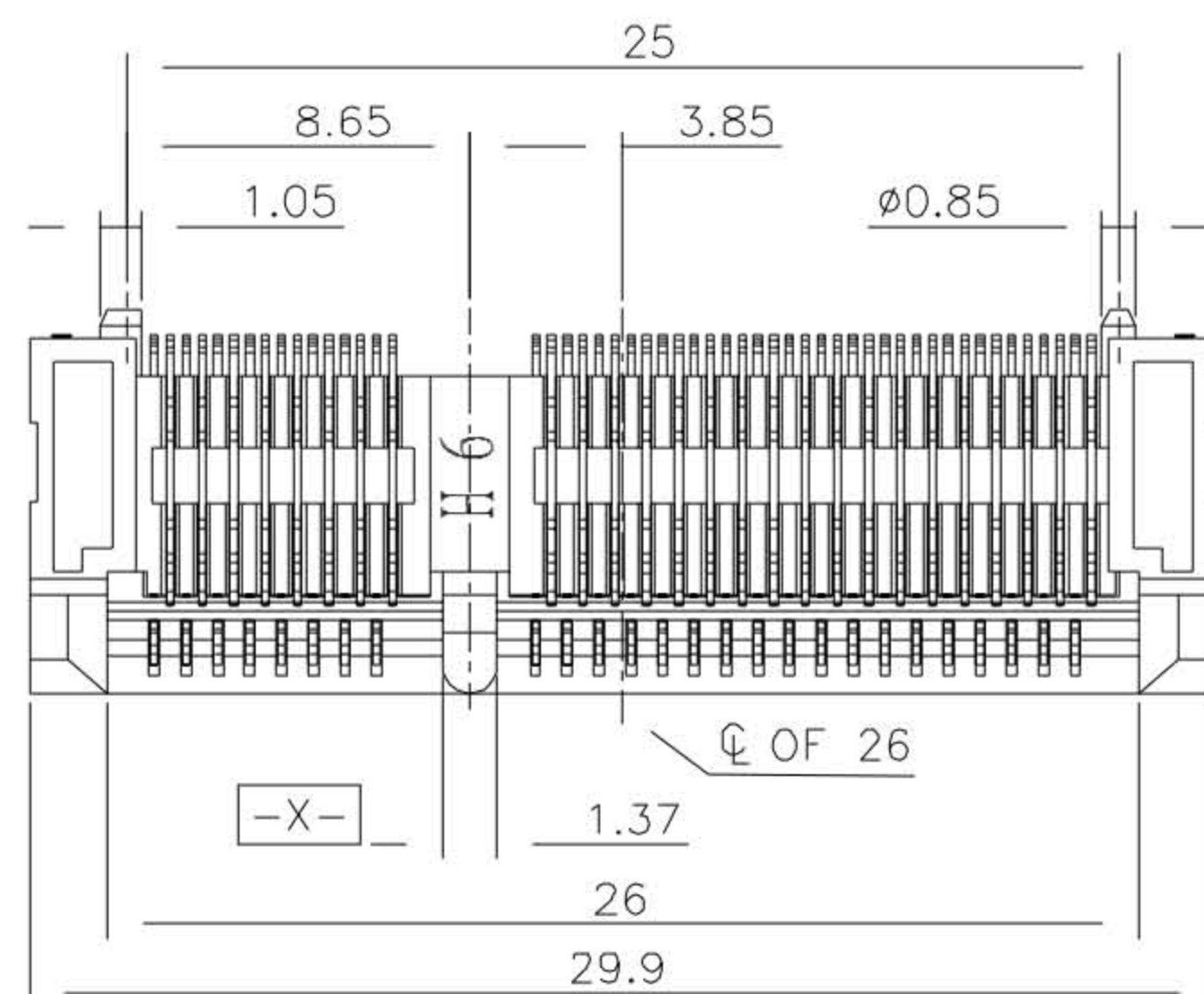
INSULATION RESISTANCE : 500 M Ω

OPERATING TEMPERATURE : $-25^{\circ}\text{C}\sim 80^{\circ}\text{C}$

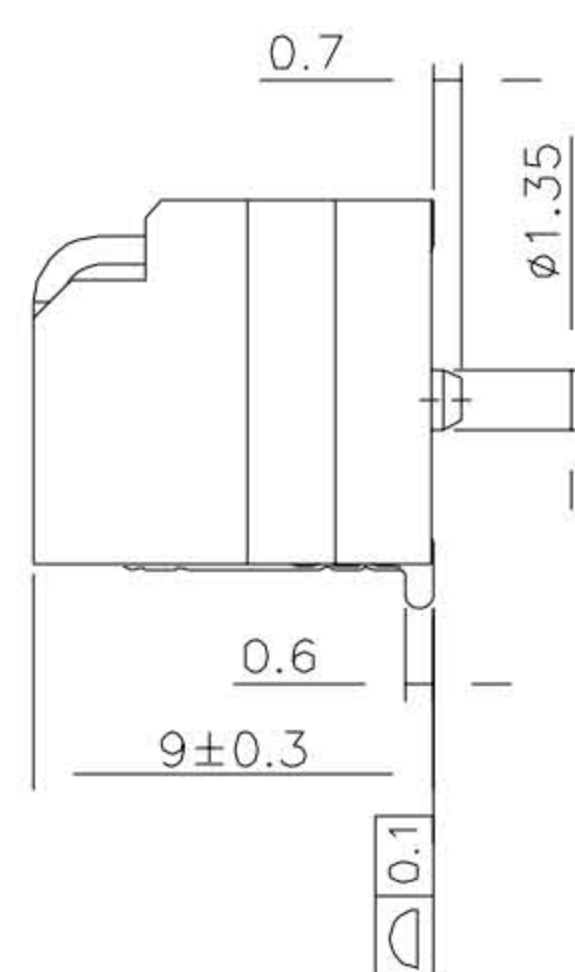
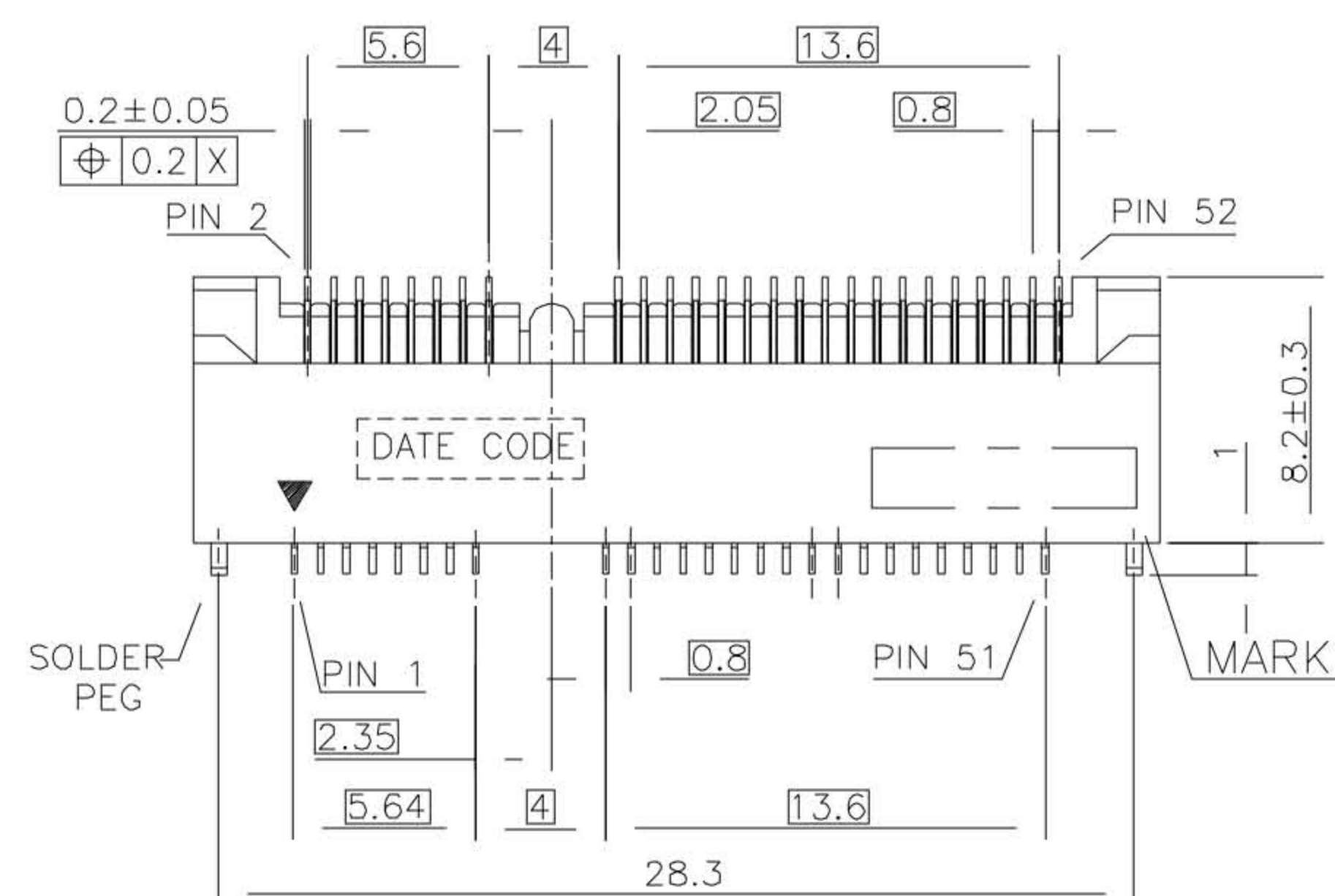
1. TOLERANCES NON-CUMULATIVE

2 LOCATION OF INSERTED CARD EDGE IS
ALIGNED WITH ϕ OF HOLES.

3. THE HORIZONTAL AXIS FOR THE PATTERN IS ESTABLISHED BY A LINE THROUGH THE CENTER OF THE $\varnothing 1.60$ AND $\varnothing 1.10$ HOLES. THE VERTICAL AXIS IS 90° TO THE HORIZONTAL AXIS, THROUGH THE CENTER OF DATUM E.



RECOMMENDED P.C.BOARD PATTERN LAYOUT
(SIDE BY SIDE)



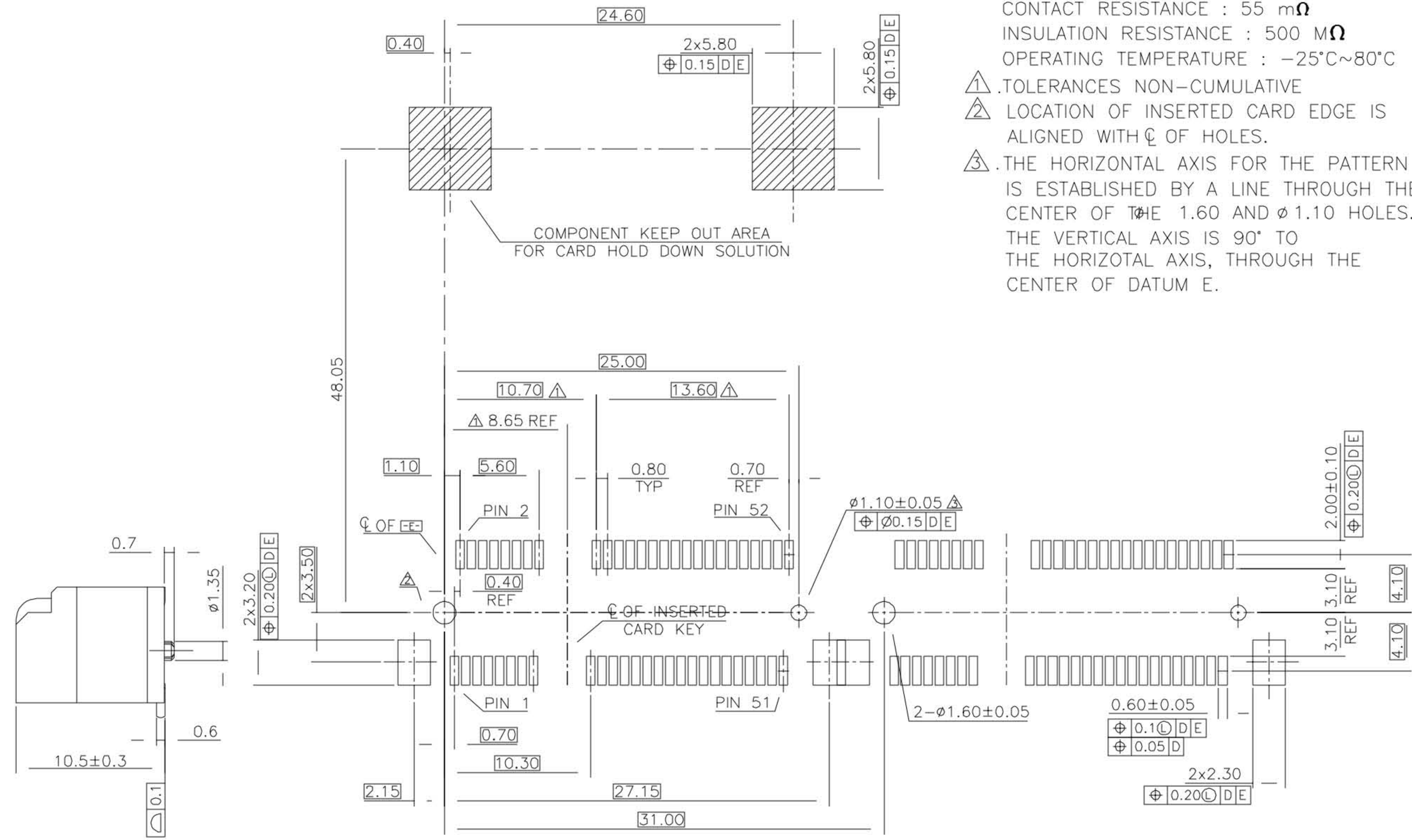
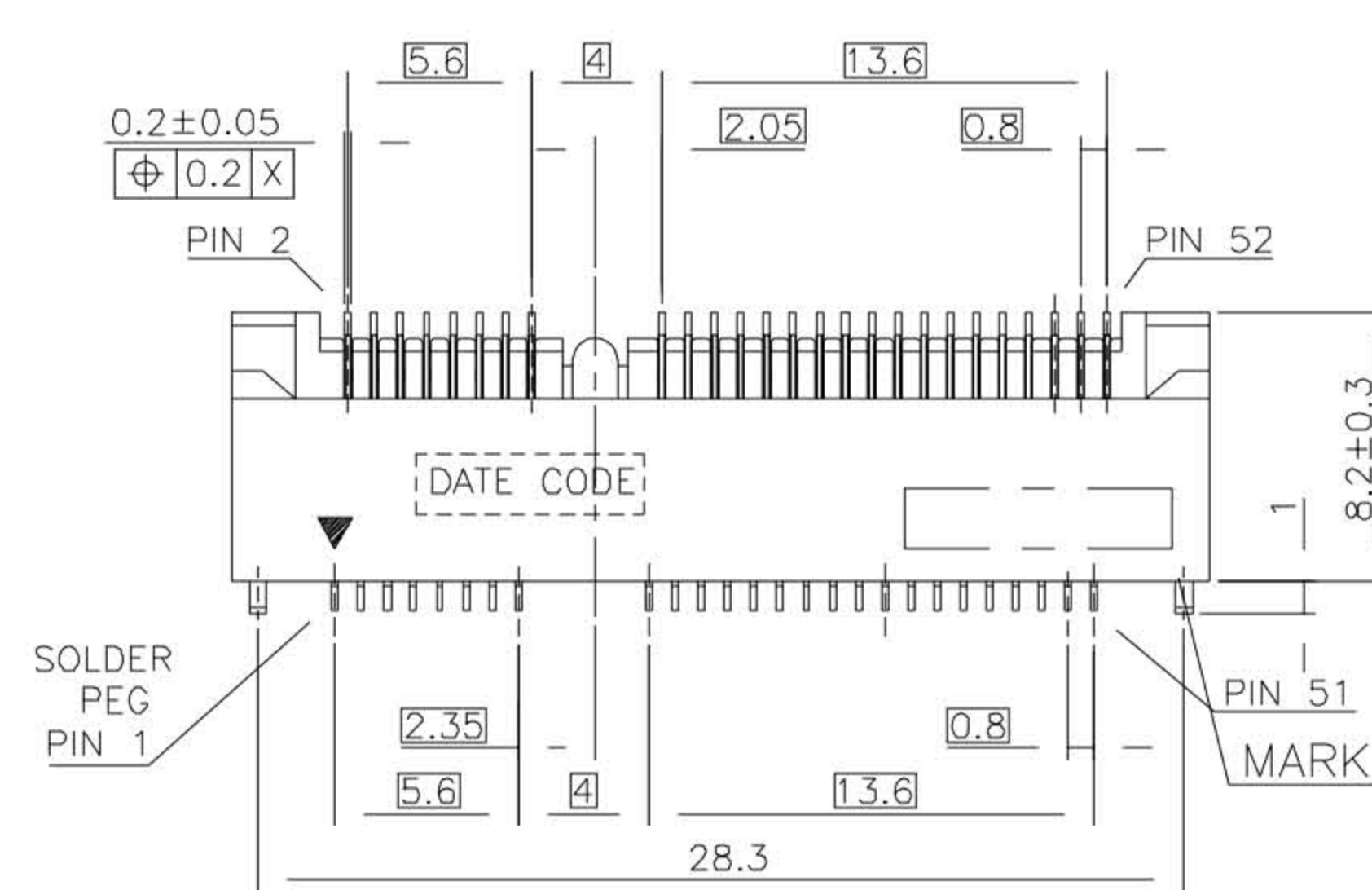
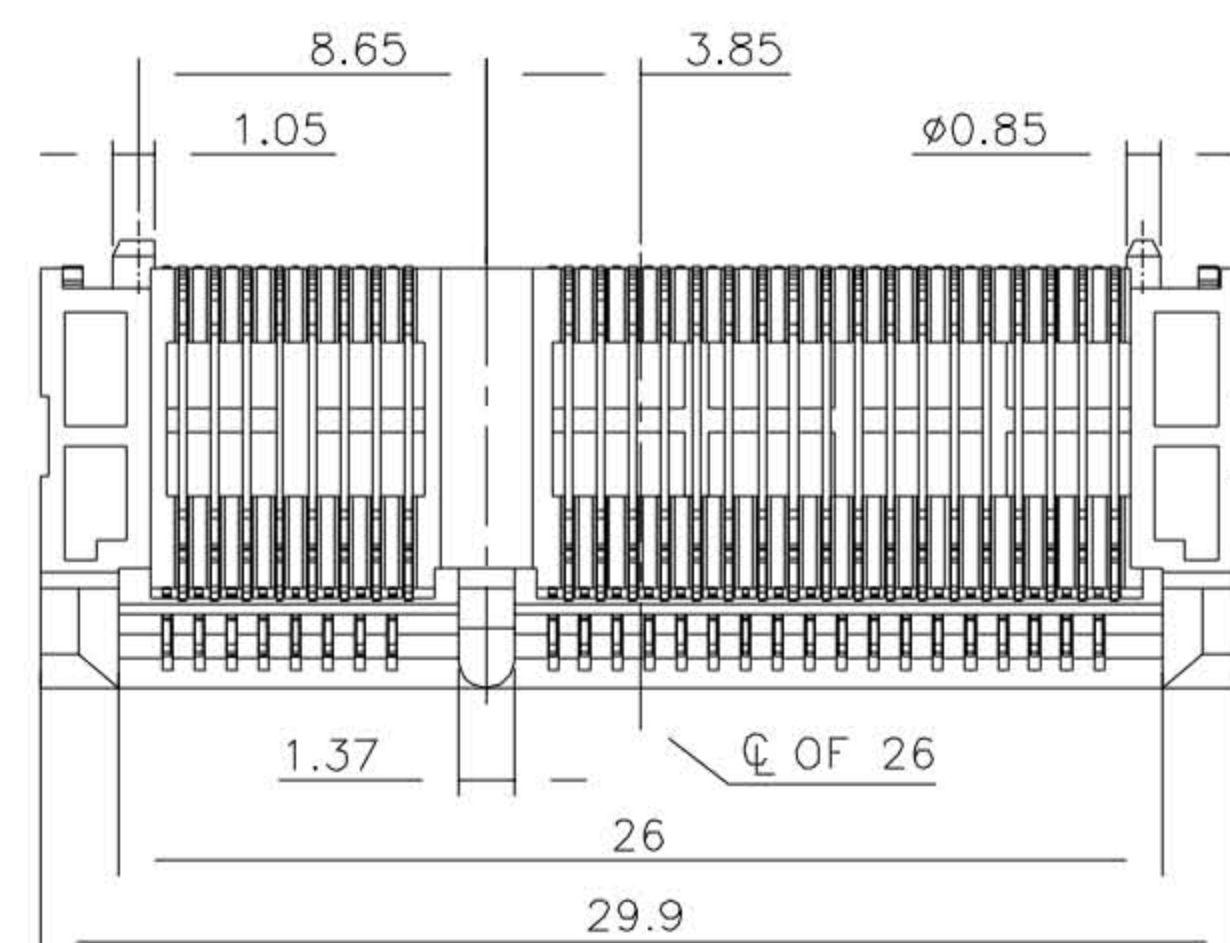
SoniTexx

INETENDED USE CUSTOMER	TITLE	0.80MM PITCH MINI PCI EXPRESS H=9.0mm CONNECTOR CUSTOMER DRAWING			
TOLERANCES	PART NO.		APPRO	Mark	
LINEAR 0.0 ±0.30 0.00±0.20 ANGLES ±3°	DRAW NO.		CHKD	Steve	
	MATERIAL	SEE NOTE	DRAW	Tina	
	FINISH	SEE NOTE	DATE	08/05/09'	
	SCALE	SHEET	REV	UNIN	
	1:1	1/1	A	mm	

ORDERING INFORMATION

SERIES NO.	CONN.TYPE	PIN NO	HEIGHT	HOUSING MATERIAL	TERMINAL PLATING	ASSIST METAL PLATING
13165-0	S	52	3	1	XX	XX

S: STANDARD 52:52PIN 3: 10.5mm 1: LCP BLACK 20: MATTE-TIN 100μ" OVER Ni 50μ" 30: BRIGHT-TIN 100μ" OVER Ni 50μ" 51: SELECTION GOLD 1μ" OVER Ni 50μ" 52: SELECTION GOLD 5μ" OVER Ni 50μ" 61: GOLD FLASH 1μ" OVER Ni 50μ" 62: GOLD FLASH 3μ" OVER Ni 50μ" 63: GOLD FLASH 4μ" OVER Ni 50μ" 65: GOLD FLASH 10μ" OVER Ni 50μ"



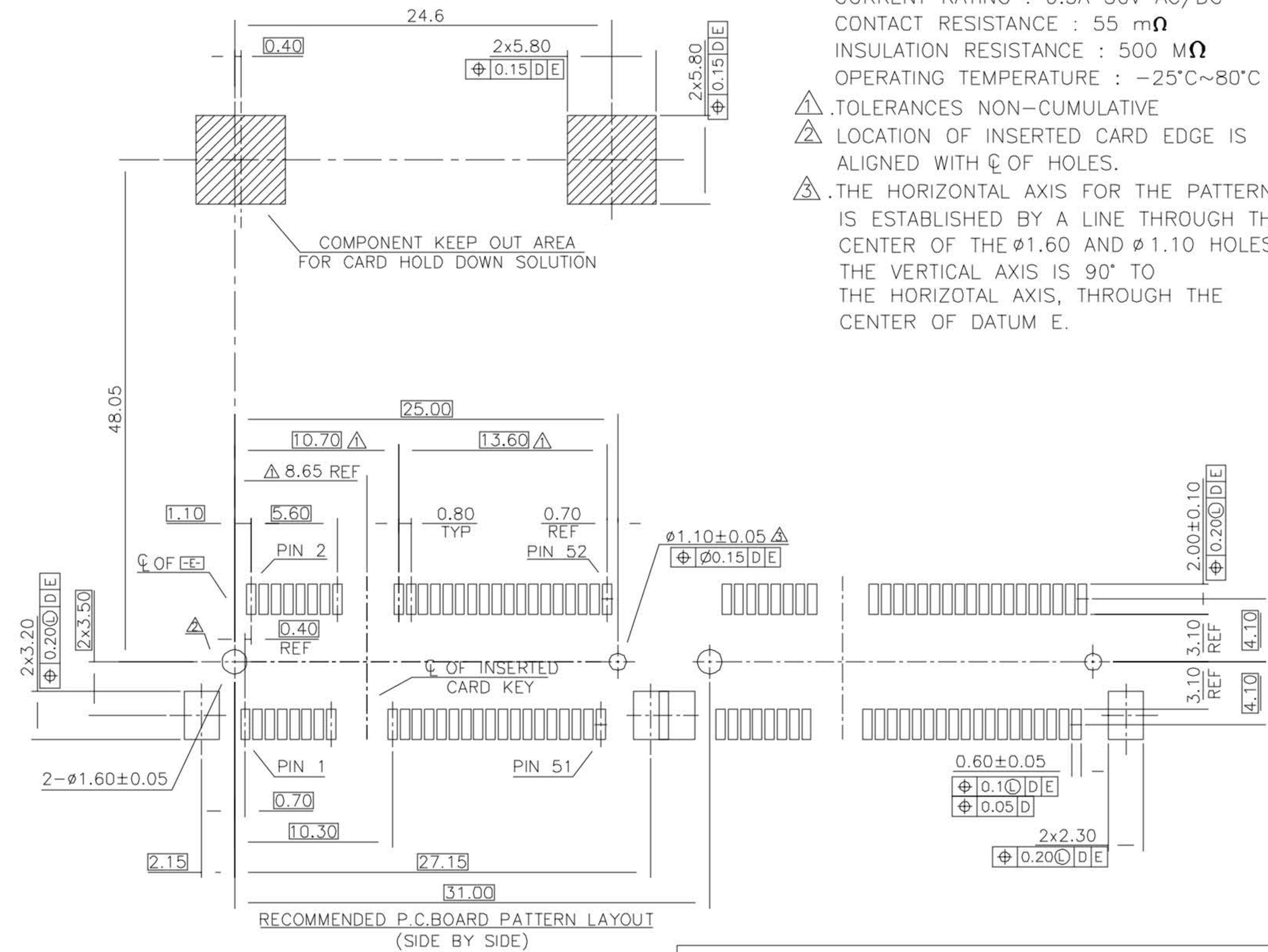
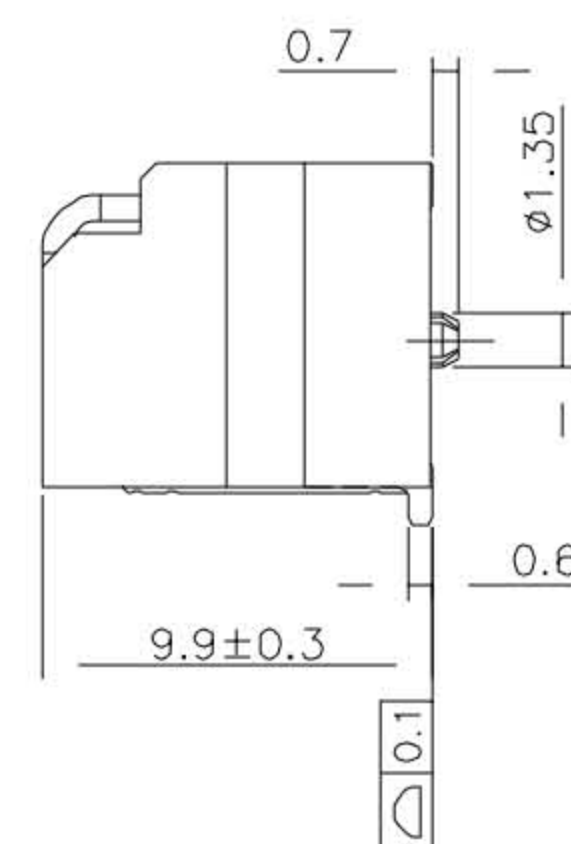
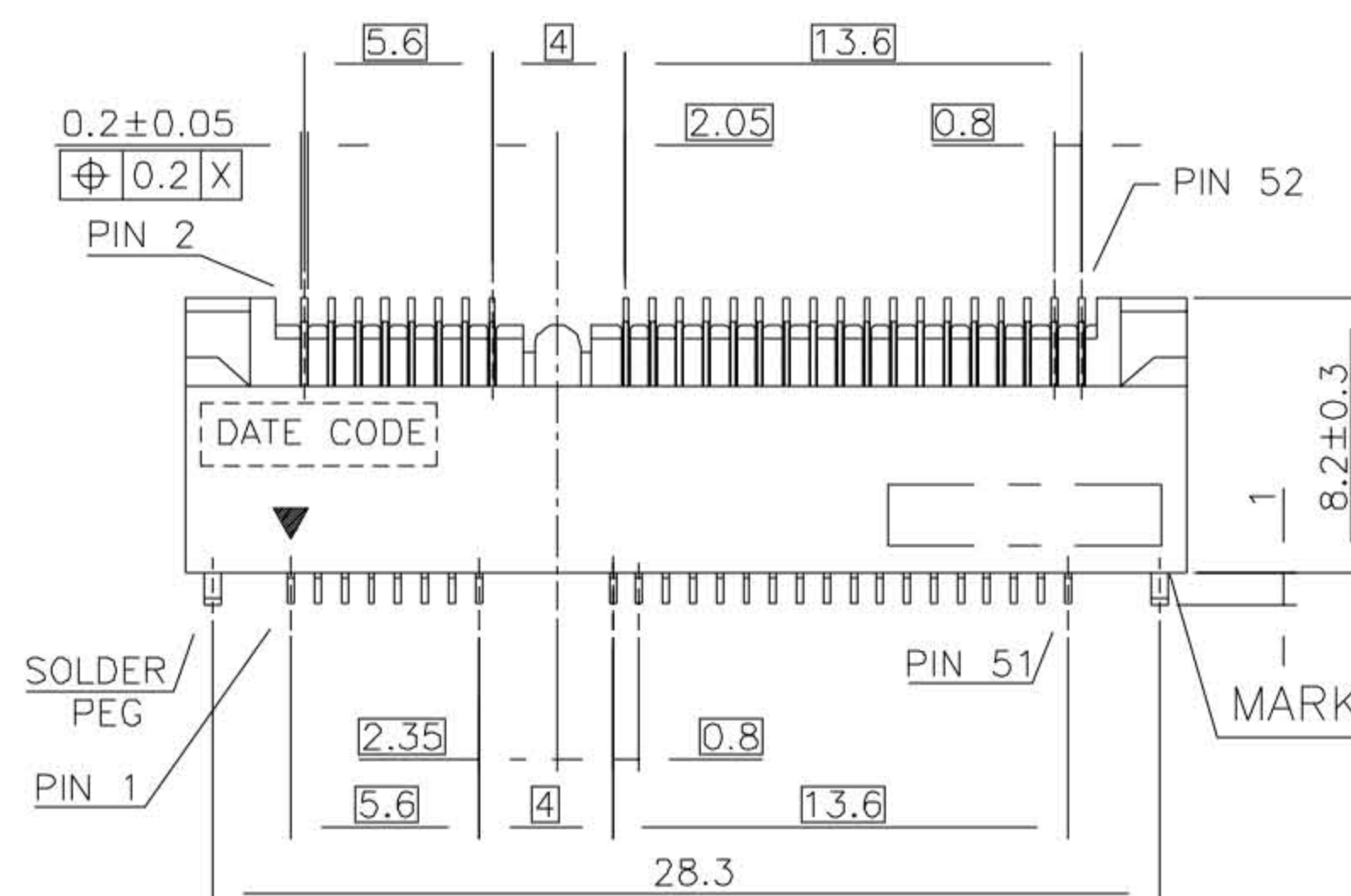
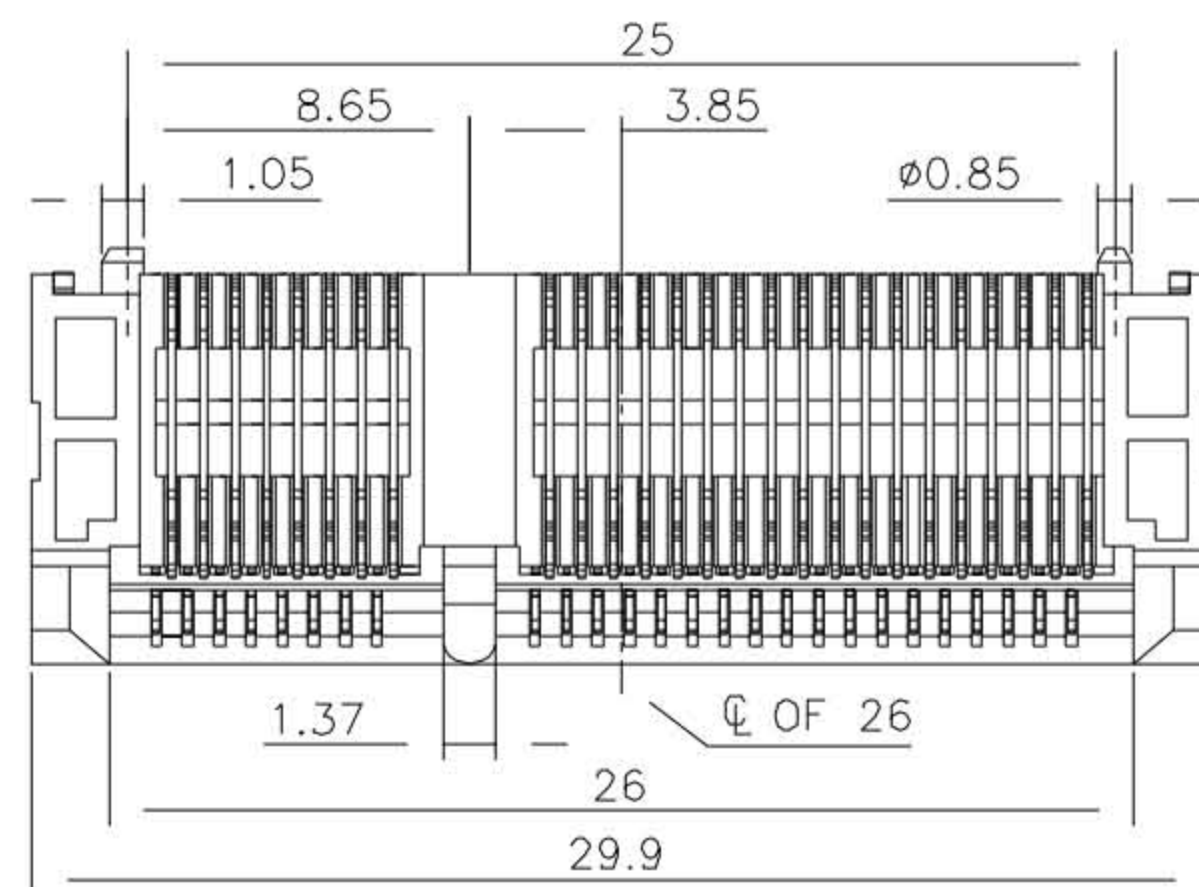
MATERIAL
 ^THIS PART DON'T CONTAIN ANY SUBSTANCES WHICH ARE SPECIFIED IN SS-00259
 HOUSING : THERMO PLASTIC UL94V-0
 CONTACT : COPPER ALLOY
 SOLDER PEG :COPPER ALLOY
 SPECIFICATION
 CURRENT RATING : 0.5A 50V AC/DC
 CONTACT RESISTANCE : 55 mΩ
 INSULATION RESISTANCE : 500 MΩ
 OPERATING TEMPERATURE : -25°C~80°C
 1. TOLERANCES NON-CUMULATIVE
 2. LOCATION OF INSERTED CARD EDGE IS ALIGNED WITH C OF HOLES.
 3. THE HORIZONTAL AXIS FOR THE PATTERN IS ESTABLISHED BY A LINE THROUGH THE CENTER OF THE 1.60 AND φ 1.10 HOLES. THE VERTICAL AXIS IS 90° TO THE HORIZONTAL AXIS, THROUGH THE CENTER OF DATUM E.

RECOMMENDED P.C. BOARD PATTERN LAYOUT (SIDE BY SIDE)

SoniTexx

INETENDED USE	CUSTOMER	TITLE	0.80MM PITCH MINI PCI EXPRESS H=10.5mm CONNECTOR CUSTOMER DRAWING			
TOLERANCES	PART NO.		APPRO	Mark		
LINEAR 0.0 ±0.30 0.00±0.20 ANGLES±3°	DRAW NO.		CHKD	Steve		
	MATERIAL	SEE NOTE	DRAW	Tina		
	FINISH	SEE NOTE	DATE	08/05/09'		
	SCALE	SHEET	REV	UNIN		
	1:1	1/1	A	mm		

SERIES NO.	CONN. TYPE	PIN NO.	HEIGHT	HOUSING MATERIAL	TERMINAL PLATING	ASSIST. METAL PLATING
13165-0	S	52	4	1	XX	XX
						20: MATTE-TIN 100μ" OVER Ni 50μ" 30: BRIGHT-TIN 100μ" OVER Ni 50μ" 51: SELECTION GOLD 1μ" OVER Ni 50μ" 52: SELECTION GOLD 5μ" OVER Ni 50μ" 61: GOLD FLASH 1μ" OVER Ni 50μ" 62: GOLD FLASH 3μ" OVER Ni 50μ" 63: GOLD FLASH 4μ" OVER Ni 50μ" 65: GOLD FLASH 10μ" OVER Ni 50μ"

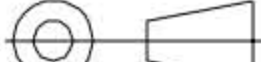


THIS PART DON'T CONTAIN ANY SUBSTANCES
WHICH ARE SPECIFIED IN SS-00259
HOUSING : THERMO PLASTIC UL94V-0
CONTACT : COPPER ALLOY
SOLDER PEG :COPPER ALLOY

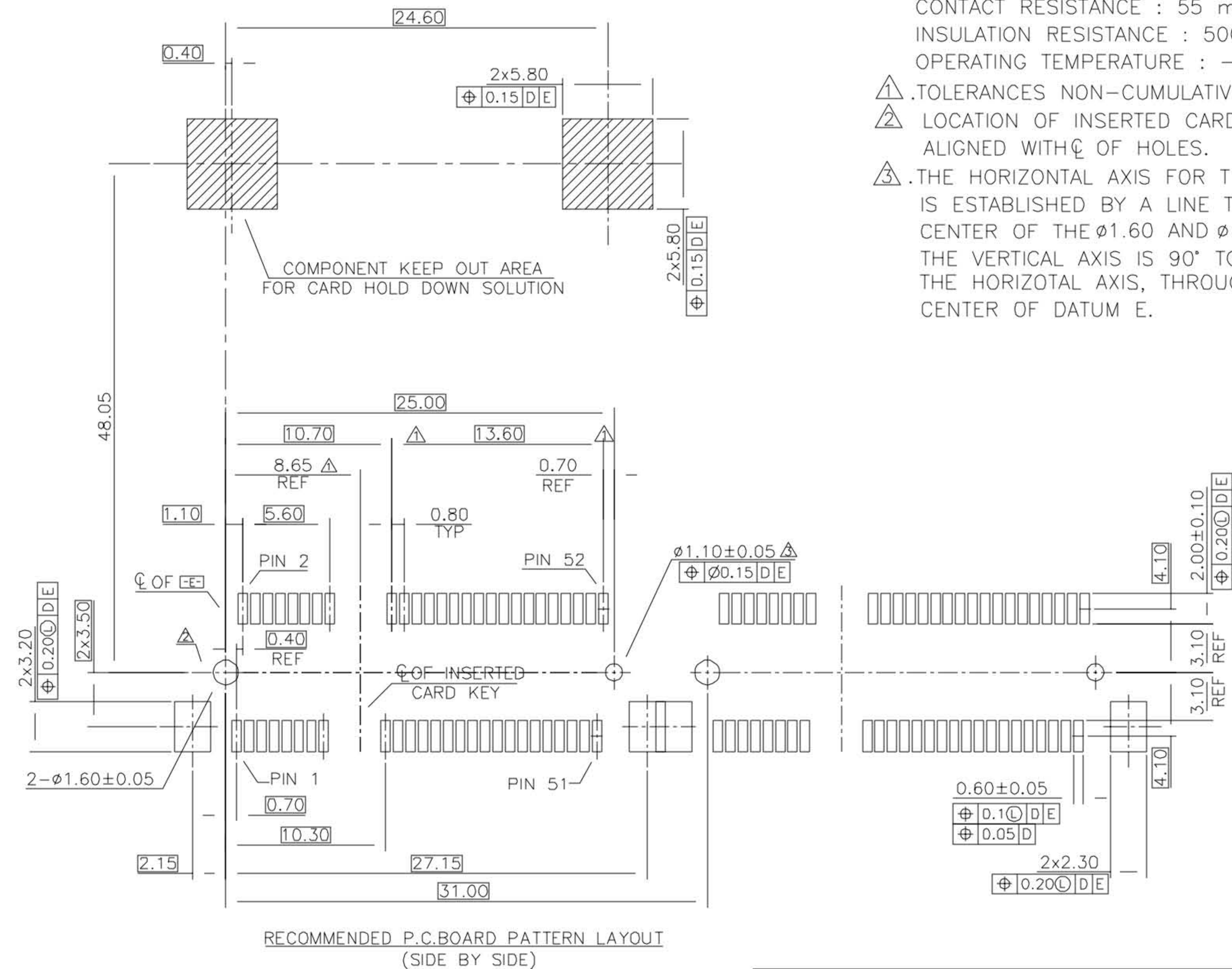
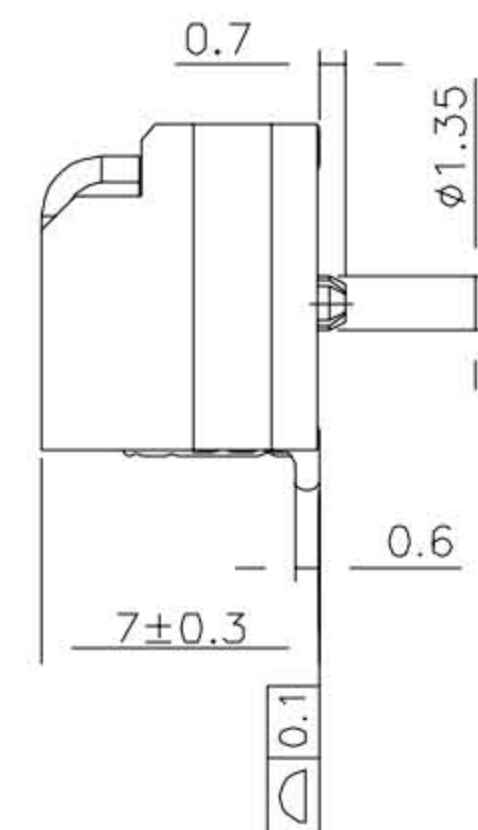
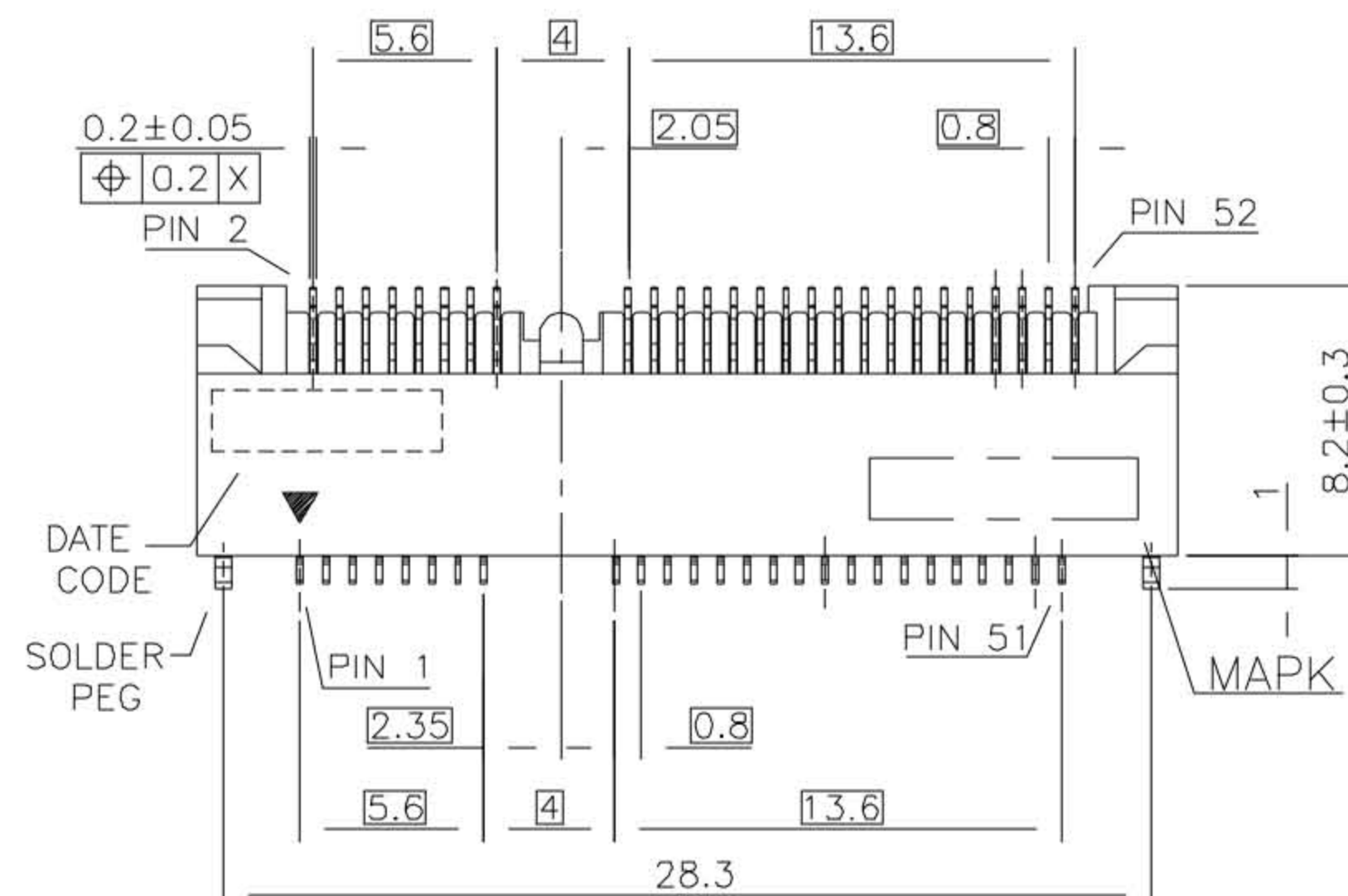
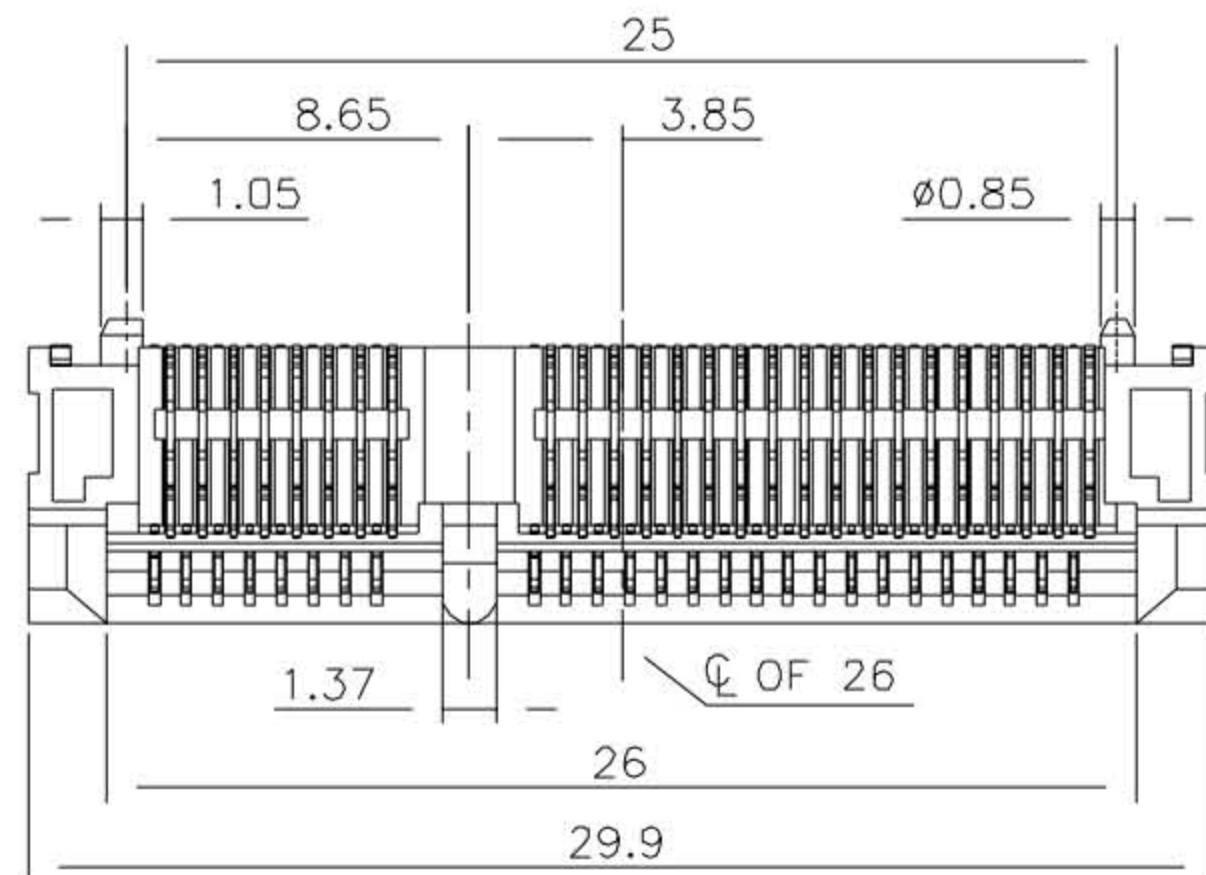
CURRENT RATING : 0.5A 50V AC/DC
CONTACT RESISTANCE : 55 mΩ
INSULATION RESISTANCE : 500 MΩ
OPERATING TEMPERATURE : -25°C~80°C

- ①. TOLERANCES NON-CUMULATIVE
- ②. LOCATION OF INSERTED CARD EDGE IS ALIGNED WITH ϕ OF HOLES.
- ③. THE HORIZONTAL AXIS FOR THE PATTERN IS ESTABLISHED BY A LINE THROUGH THE CENTER OF THE $\phi 1.60$ AND $\phi 1.10$ HOLES. THE VERTICAL AXIS IS 90° TO THE HORIZONTAL AXIS, THROUGH THE CENTER OF DATUM E.

SoniTexx

INETENDED USE CUSTOMER	TITLE	0.80MM PITCH MINI PCI EXPRESS H=9.9mm CONNECTOR CUSTOMER DRAWING			
TOLERANCES	PART NO.		APPRO	Mark	
LINEAR 0.0 ±0.30 0.00±0.20 ANGLES±3°	DRAW NO.		CHKD	Steve	
	MATERIAL	SEE NOTE	DRAW	Tina	
	FINISH	SEE NOTE	DATE	08/05/09'	
	SCALE 1:1	SHEET 1/1	REV A	UNIN mm	

SERIES NO.	CONN. TYPE	PIN NO.	HEIGHT	HOUSING MATERIAL	TERMINAL PLATING	ASSIST. METAL PLATING
13165-0	S	52	5	1	XX	XX
						20: MATTE-TIN 100μ" OVER Ni 50μ" 30: BRIGHT-TIN 100μ" OVER Ni 50μ" 51: SELECTION GOLD 1μ" OVER Ni 50μ" 52: SELECTION GOLD 5μ" OVER Ni 50μ" 61: GOLD FLASH 1μ" OVER Ni 50μ" 62: GOLD FLASH 3μ" OVER Ni 50μ" 63: GOLD FLASH 4μ" OVER Ni 50μ" 65: GOLD FLASH 10μ" OVER Ni 50μ"



THIS PART DON'T CONTAIN ANY SUBSTANCES
WHICH ARE SPECIFIED IN SS-00259
HOUSING : THERMO PLASTIC UL94V-0
CONTACT : COPPER ALLOY
SOLDER PEG :COPPER ALLOY

CURRENT RATING : 0.5A 50V AC/DC
CONTACT RESISTANCE : 55 mΩ
INSULATION RESISTANCE : 500 MΩ
OPERATING TEMPERATURE : -25°C~80°C

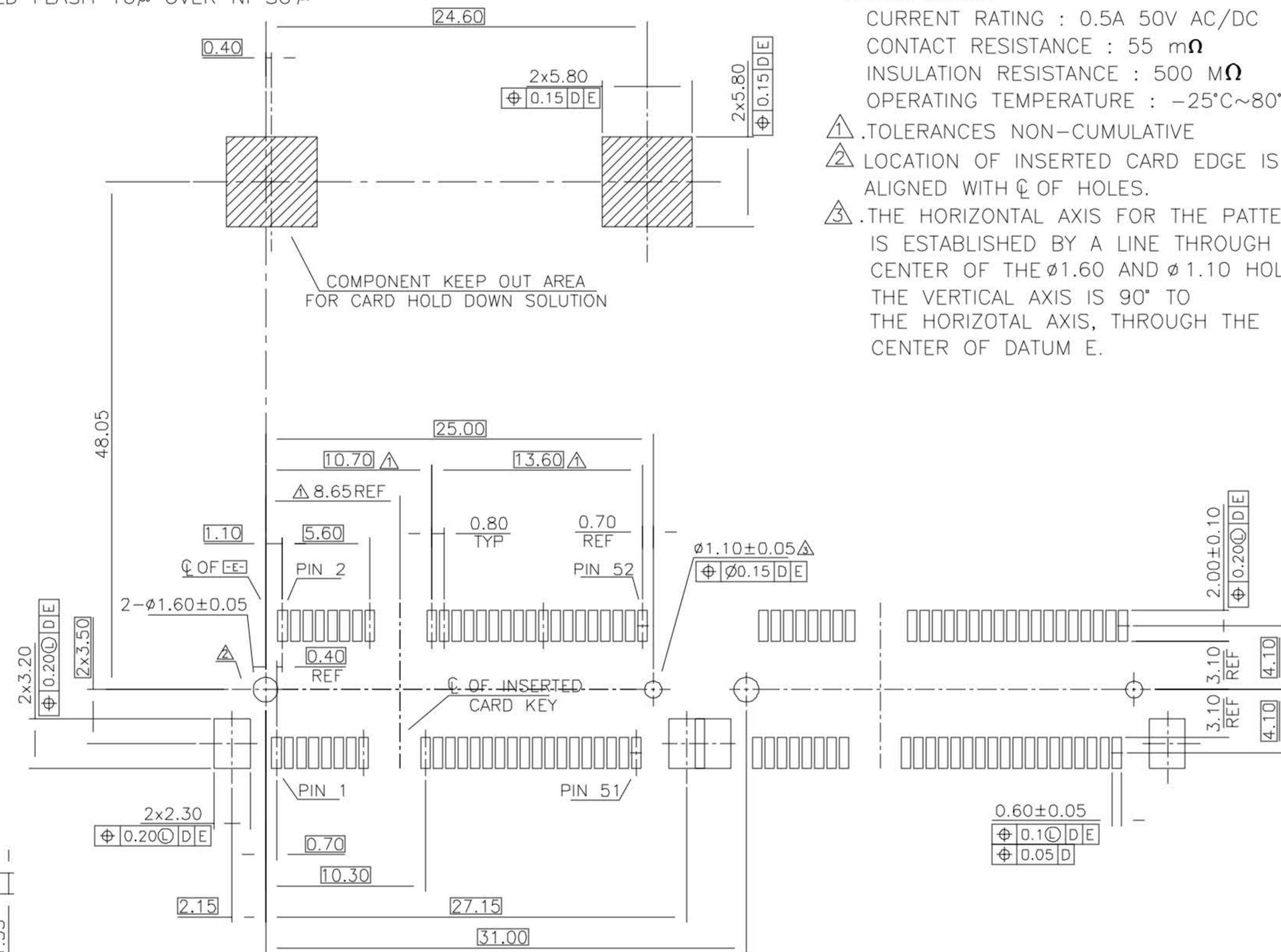
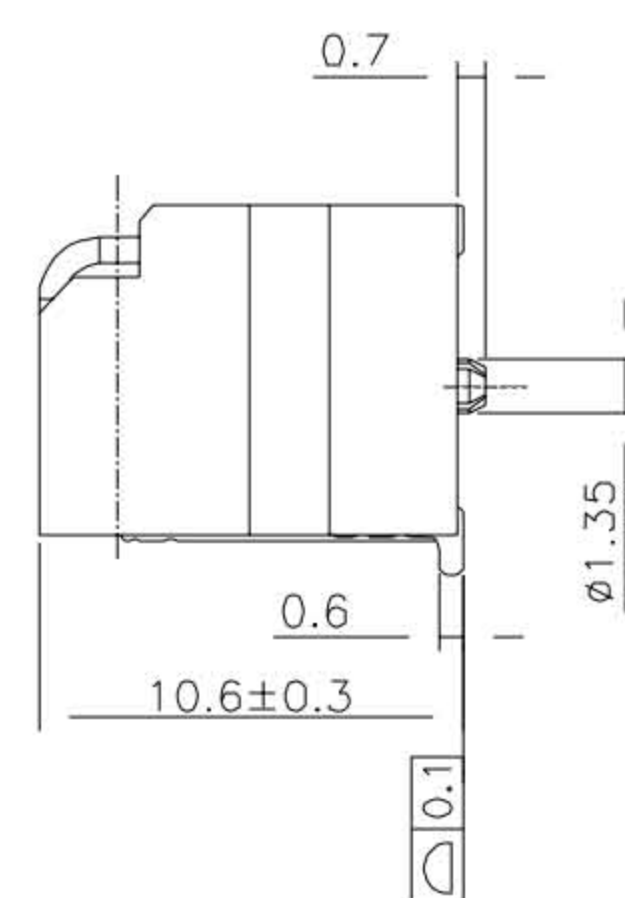
- ①. TOLERANCES NON-CUMULATIVE
- ②. LOCATION OF INSERTED CARD EDGE IS ALIGNED WITH ϕ OF HOLES.
- ③. THE HORIZONTAL AXIS FOR THE PATTERN IS ESTABLISHED BY A LINE THROUGH THE CENTER OF THE $\phi 1.60$ AND $\phi 1.10$ HOLES. THE VERTICAL AXIS IS 90° TO THE HORIZONTAL AXIS, THROUGH THE CENTER OF DATUM E.

		SoniTexx			
INETENDED USE CUSTOMER	TITLE	0.80MM PITCH MINI PCI EXPRESS H=7.0mm CONNECTOR CUSTOMER DRAWING			
TOLERANCES	PART NO.		APPRO	Mark	
LINEAR 0.0 ±0.30 0.00±0.20 ANGLES±3°	DRAW NO.		CHKD	Steve	
	MATERIAL	SEE NOTE	DRAW	Tina	
	FINISH	SEE NOTE	DATE	08/05/09'	
	SCALE 1:1	SHEET 1/1	REV A	UNIN mm	

ASSIST METAL PLATING

20: MATTE-TIN 100 μ "	20: MATTE-TIN
OVER Ni 50 μ "	30: BRIGHT-TIN
30: BRIGHT-TIN 100 μ "	
OVER Ni 50 μ "	
51: SELECTION GOLD 1 μ " OVER Ni 50 μ "	
52: SELECTION GOLD 5 μ " OVER Ni 50 μ "	
61: GOLD FLASH 1 μ " OVER Ni 50 μ "	
62: GOLD FLASH 3 μ " OVER Ni 50 μ "	
63: GOLD FLASH 4 μ " OVER Ni 50 μ "	
65: GOLD FLASH 10 μ " OVER Ni 50 μ "	

△. THE HORIZONTAL AXIS FOR THE PATTERN IS ESTABLISHED BY A LINE THROUGH THE CENTER OF THE Ø1.60 AND Ø1.10 HOLES. THE VERTICAL AXIS IS 90° TO THE HORIZONTAL AXIS, THROUGH THE CENTER OF DATUM E.



SoniTexx

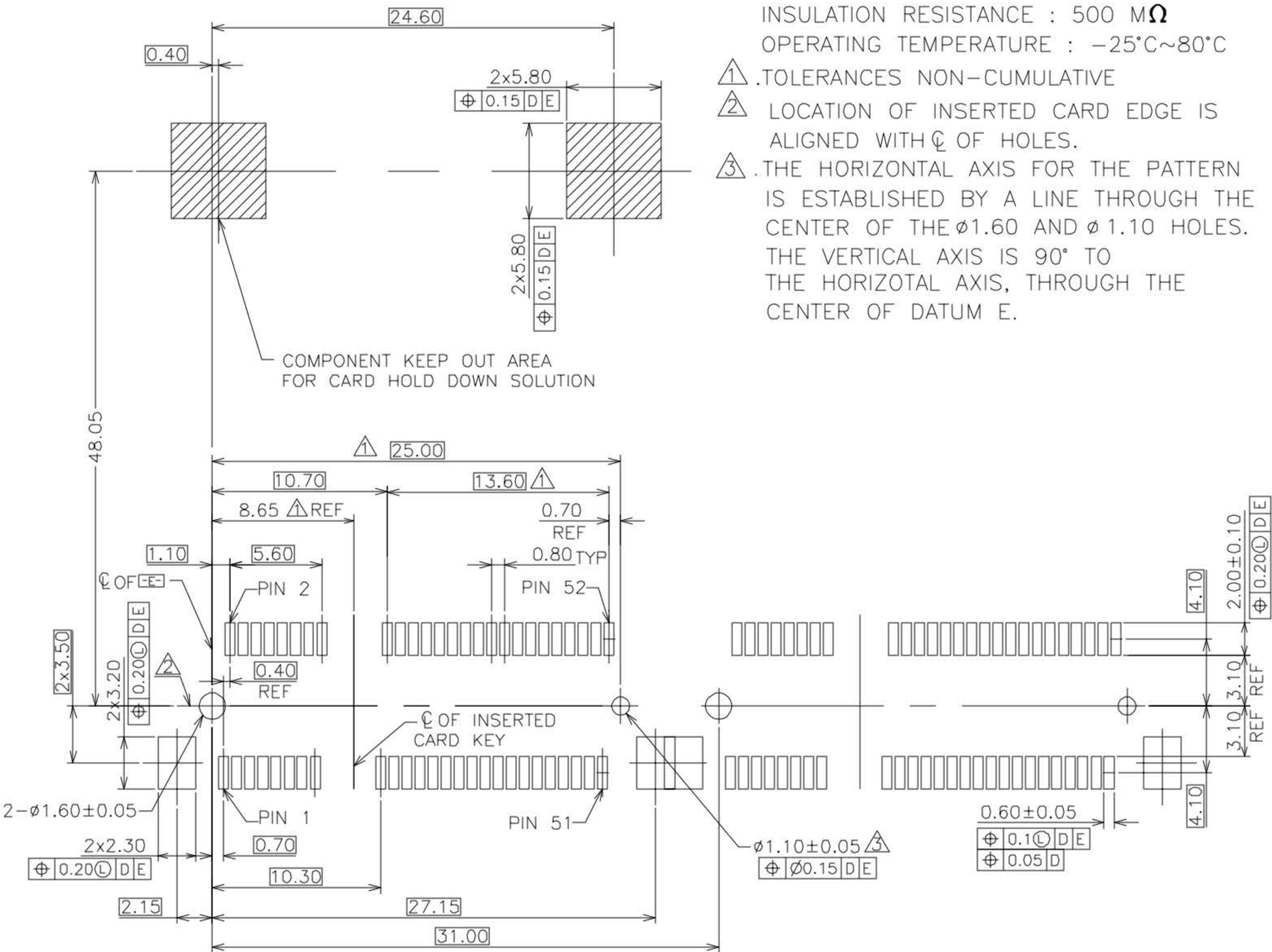
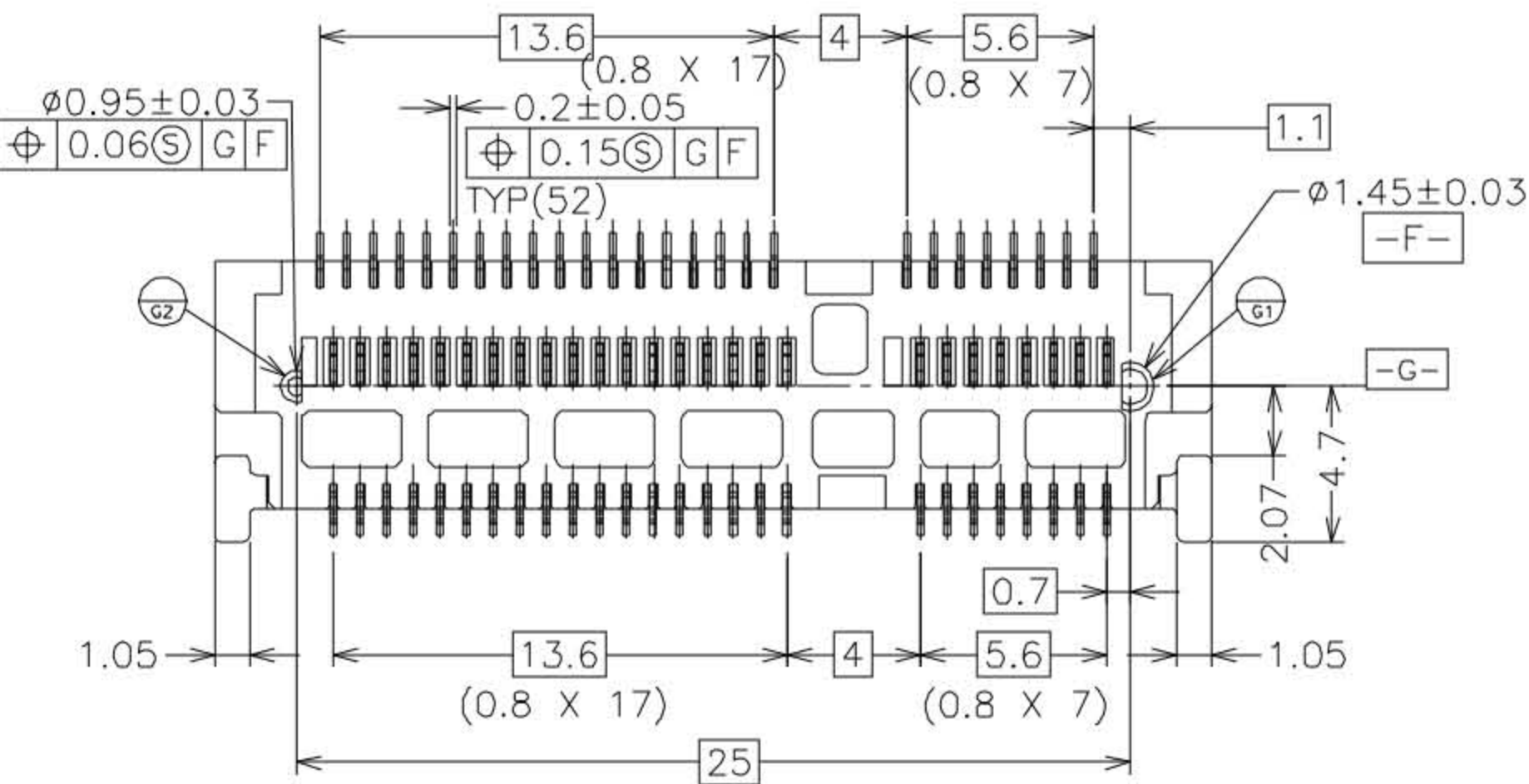
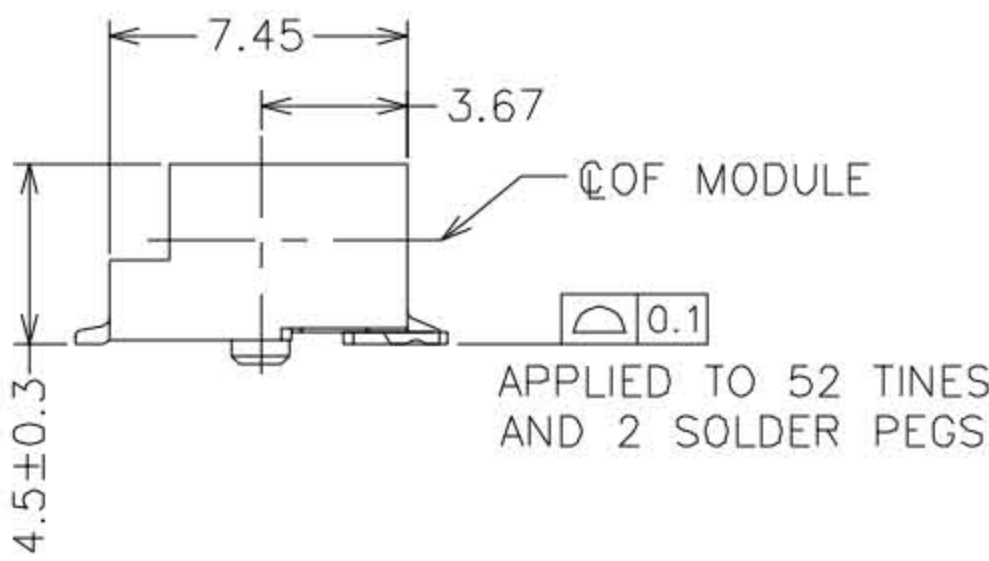
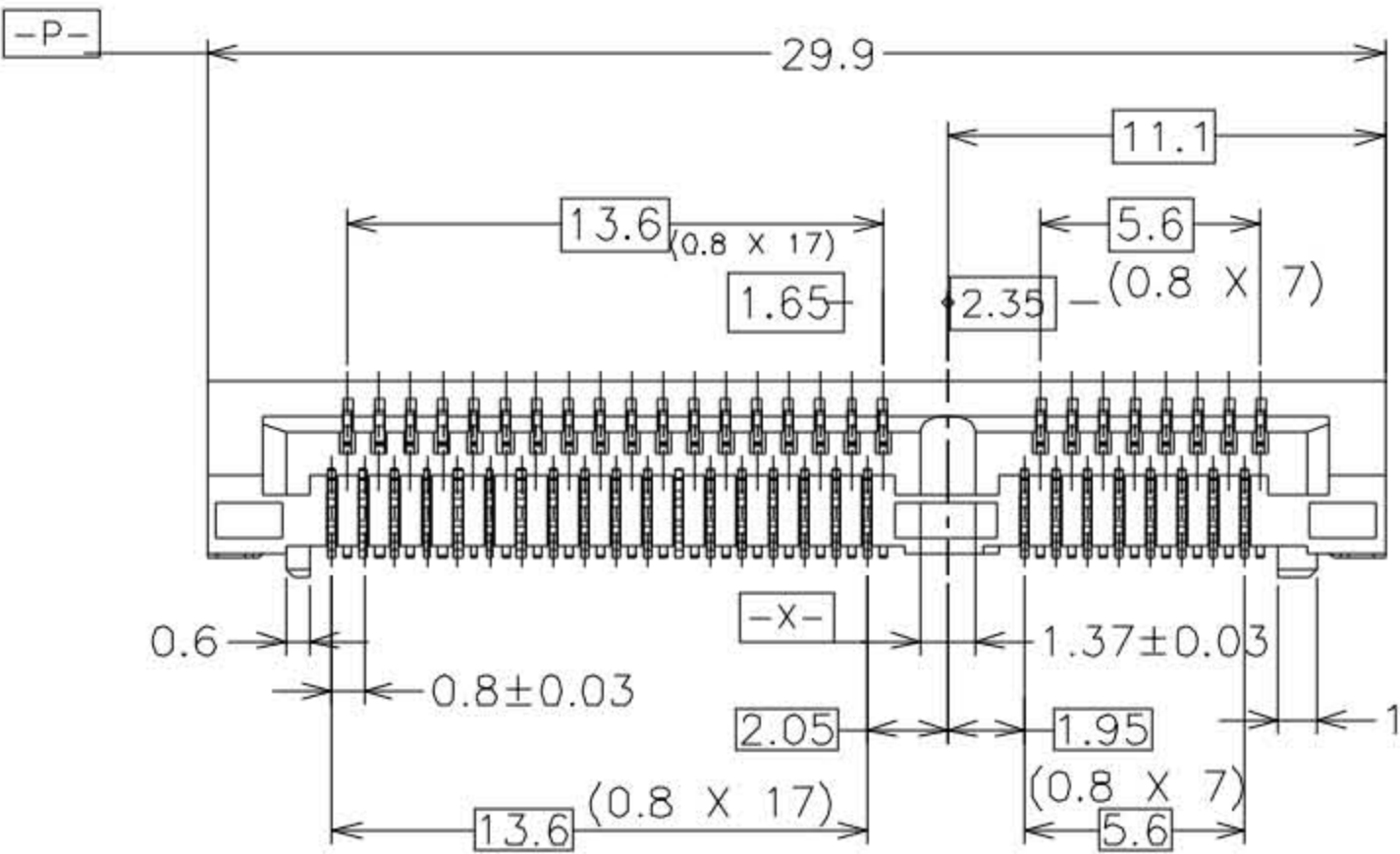
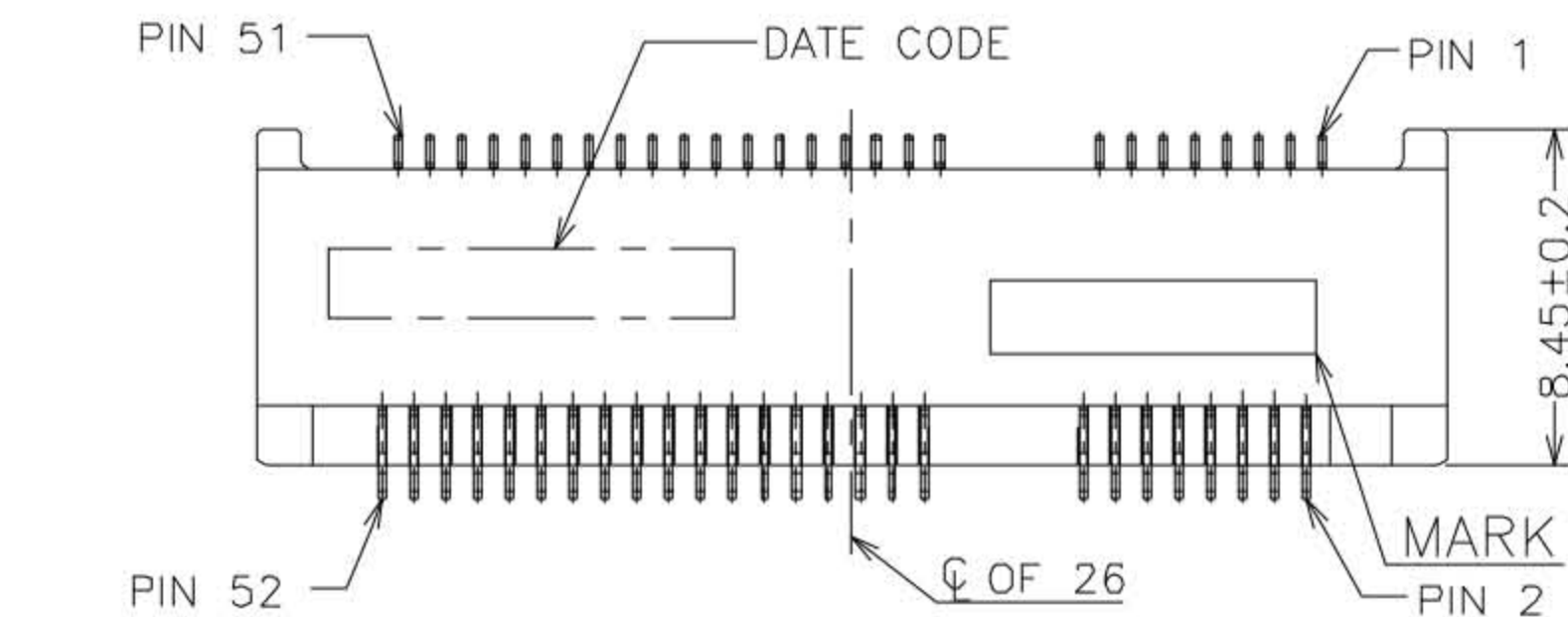
INETENDED USE CUSTOMER	TITLE	0.80MM PITCH MINI PCI EXPRESS H=10.6mm CONNECTOR CUSTOMER DRAWING			
TOLERANCES	PART NO.		APPRO	Mark	
LINEAR 0.0 ±0.30 0.00±0.20 ANGLES±3°	DRAW NO.		CHKD	Steve	
	MATERIAL	SEE NOTE	DRAW	Tina	
	FINISH	SEE NOTE	DATE	08/05/09'	
	SCALE	SHEET	REV	UNIN	
	1:1	1/1	A	mm	

ORDERING INFORMATION						
SERIES NO.	CONN.TYPE	PIN NO	HEIGHT	HOUSING MATERIAL	TERMINAL PLATING	ASSIST METAL PLATING
13165-5	S	52	6	2	XX	XX
S: STANDARD 52PIN 6: 4.50mm 2: LCP BLACK 20: MATTE-TIN 100μ" OVER Ni 50μ" 20: MATTE-TIN 30: BRIGHT-TIN 100μ" OVER Ni 50μ"						

- 51: SELECTION GOLD 1μ" OVER Ni 50μ"
52: SELECTION GOLD 5μ" OVER Ni 50μ"
61: GOLD FLASH 1μ" OVER Ni 50μ"
62: GOLD FLASH 3μ" OVER Ni 50μ"
63: GOLD FLASH 4μ" OVER Ni 50μ"
65: GOLD FLASH 10μ" OVER Ni 50μ"
66: CONTACT AREA GOLD PLATING 1μ" SOLDER TAIL MATTE-TIN 120~180μ" ALL OVER Ni 50~80μ"
67: CONTACT AREA GOLD PLATING 3μ" SOLDER TAIL MATTE-TIN 120~180 ALL OVER Ni 50~80μ"
71: CONTACT AREA AND SOLDER AREA : SELECTION GOLD 1μ" OVER Ni 50~80μ"
72: CONTACT AREA AND SOLDER AREA : SELECTION GOLD 3μ" OVER Ni 50~80μ"

MATERIAL
^THIS PART DON'T CONTAIN ANY SUBSTANCES WHICH ARE SPECIFIED IN SS-00259
HOUSING : THERMO PLASTIC UL94V-0
CONTACT : COPPER ALLOY
SOLDER PEG :COPPER ALLOY
SPECIFICATION
CURRENT RATING : 0.5A 50V AC/DC
CONTACT RESISTANCE : 55 mΩ
INSULATION RESISTANCE : 500 MΩ
OPERATING TEMPERATURE : -25°C~80°C

- △.TOLERANCES NON-CUMULATIVE
△ LOCATION OF INSERTED CARD EDGE IS ALIGNED WITH ϕ OF HOLES.
△ THE HORIZONTAL AXIS FOR THE PATTERN IS ESTABLISHED BY A LINE THROUGH THE CENTER OF THE $\phi 1.60$ AND $\phi 1.10$ HOLES. THE VERTICAL AXIS IS 90° TO THE HORIZOTAL AXIS, THROUGH THE CENTER OF DATUM E.



SoniTexx

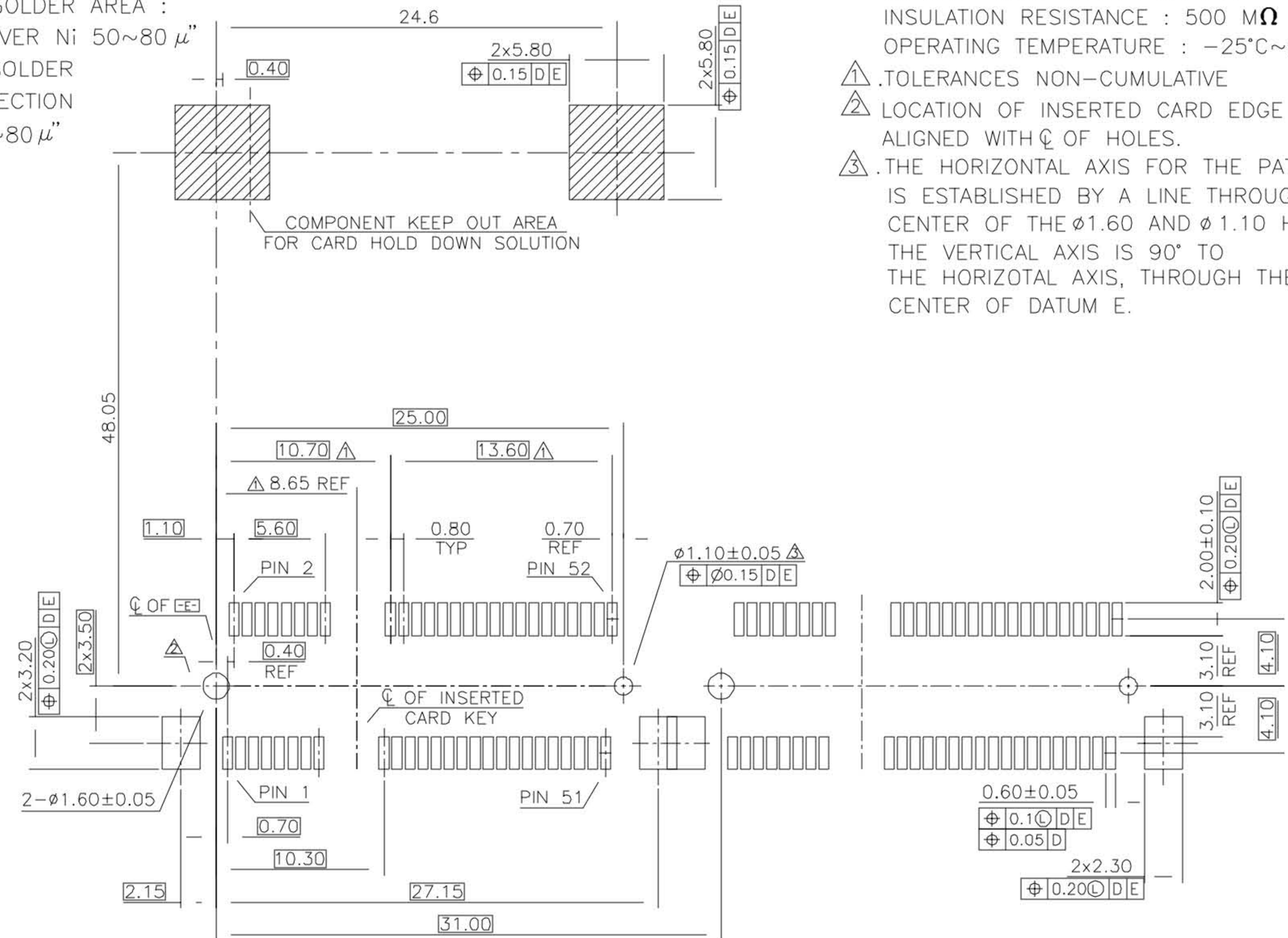
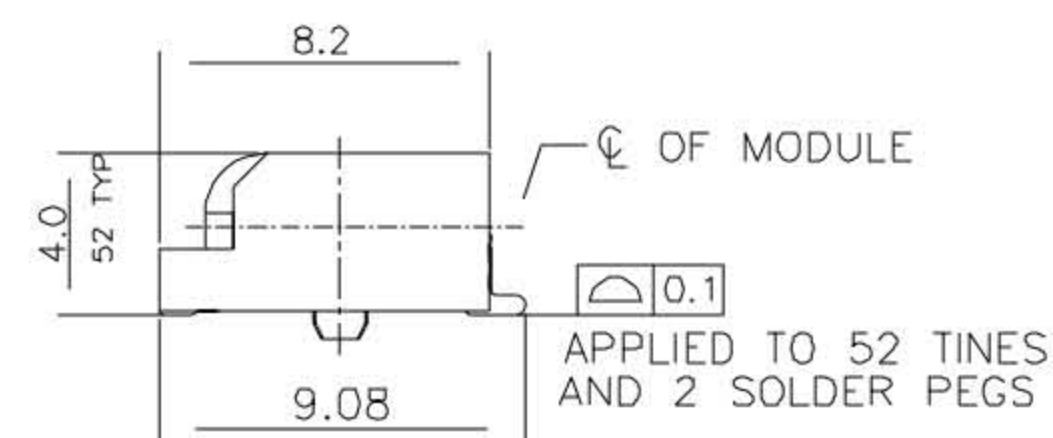
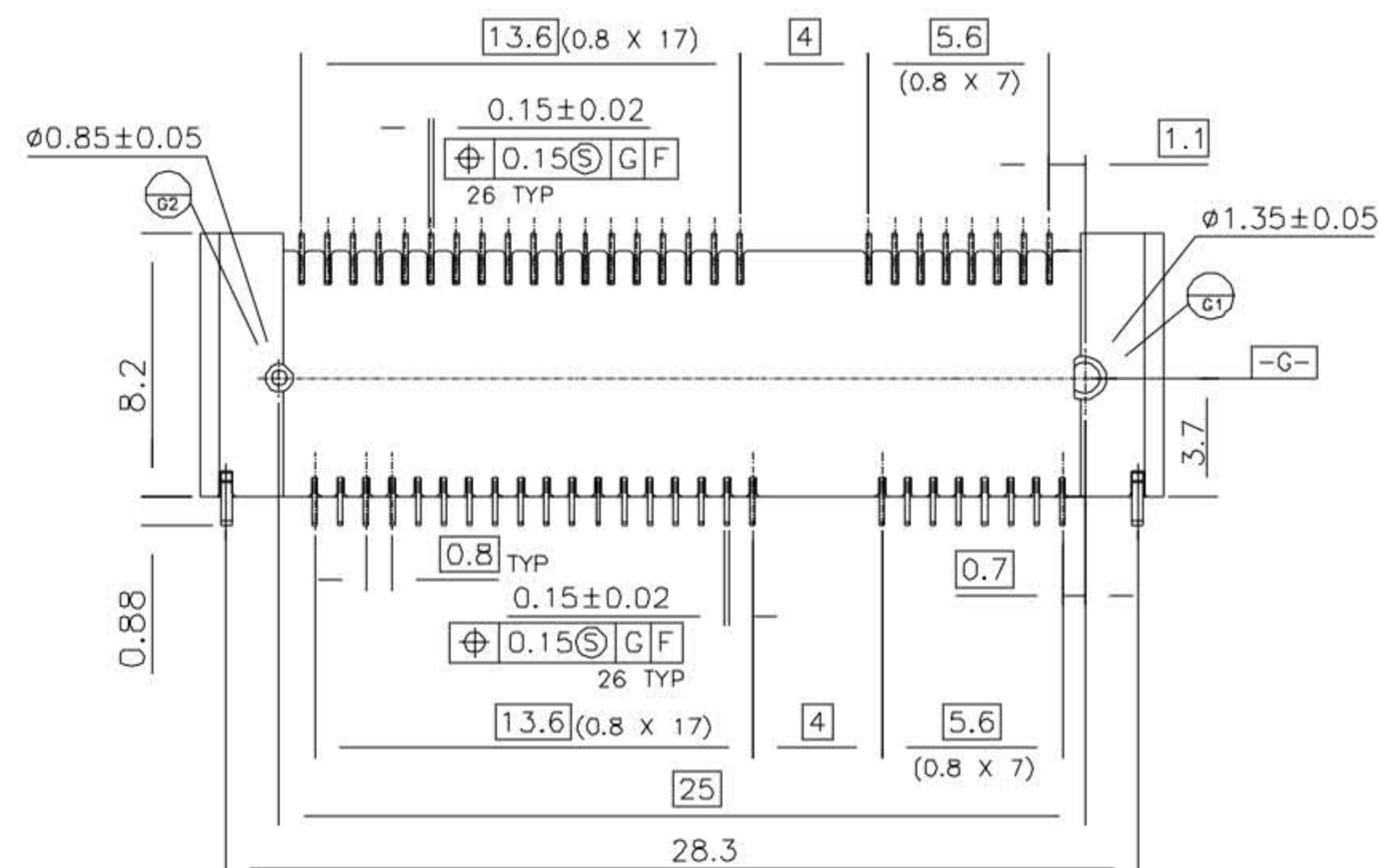
INETENDED USE	TITLE				
CUSTOMER	0.80MM PITCH MINI PCI EXPRESS H=4.5mm CONNECTOR CUSTOMER DRAWING				
TOLERANCES	PART NO.		APPRO	Mark	
LINEAR 0.0 ±0.30 0.00±0.20 ANGLES ±3°	DRAW NO.		CHKD	Steve	
	MATERIAL	SEE NOTE	DRAW	Tina	
	FINISH	SEE NOTE	DATE	08/05/09'	
	SCALE	SHEET	REV	UNIN	
	1:1	1/1	A	mm	

ASSIST METAL
PLATING

XX

20: MATTE-TIN
, 30: BRIGHT-TIN

73: CONTACT AREA AND SOLDER
AREA :SINGLE SIDE SELECTION
GOLD 1μ " OVER Ni 50~80 μ "



RECOMMENDED P.C.BOARD PATTERN LAYOUT
(SIDE BY SIDE)

3. THE HORIZONTAL AXIS FOR THE PATTERN IS ESTABLISHED BY A LINE THROUGH THE CENTER OF THE $\varnothing 1.60$ AND $\varnothing 1.10$ HOLES. THE VERTICAL AXIS IS 90° TO THE HORIZONTAL AXIS, THROUGH THE CENTER OF DATUM E.

SoniTexx

INETENDED USE CUSTOMER	TITLE	0.80MM PITCH MINI PCI EXPRESS H=4.0mm CONNECTOR CUSTOMER DRAWING			
TOLERANCES	PART NO.		APPRO	Mark	
LINEAR 0.0 ± 0.30 0.00 ± 0.20	DRAW NO.		CHKD	Steve	
ANGLES $\pm 3^\circ$	MATERIAL	SEE NOTE	DRAW	Tina	
	FINISH	SEE NOTE	DATE	08/05/09'	
	SCALE	SHEET	REV	UNIN	
	1:1	1/1	A	mm	

